



HMBT2369

NPN EPITAXIAL PLANAR TRANSISTOR

Description

The HMBT2369 is designed for general purpose switching and amplifier applications.

Features

- Low Collector Saturation Voltage
- High speed switching Transistor

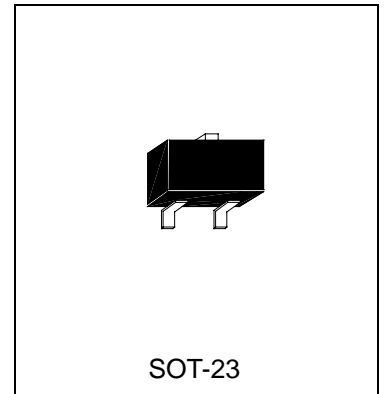
Absolute Maximum Ratings

- Maximum Temperatures
Storage Temperature -55 ~ +150 °C
Junction Temperature +150 °C Maximum
- Maximum Power Dissipation
Total Power Dissipation (Ta=25°C) 225 mW
- Maximum Voltages and Currents (Ta=25°C)
VCBO Collector to Base Voltage 40 V
VCEO Collector to Emitter Voltage 15 V
VEBO Emitter to Base Voltage 4.5 V
IC Collector Current 500 mA

Characteristics (Ta=25°C)

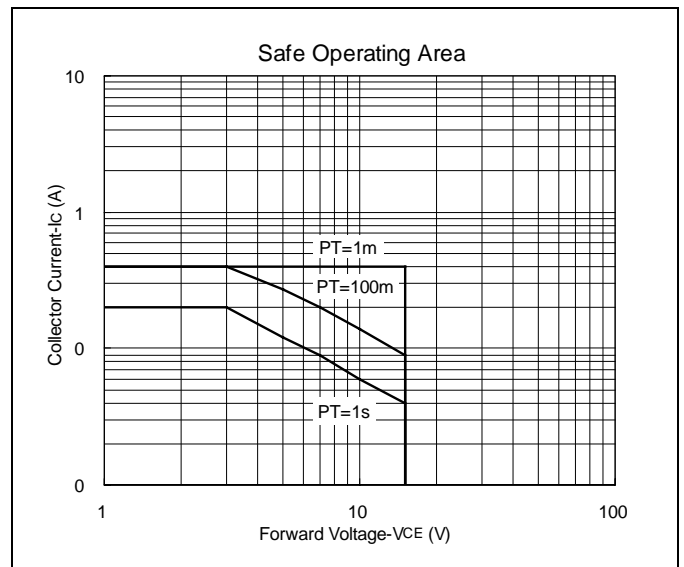
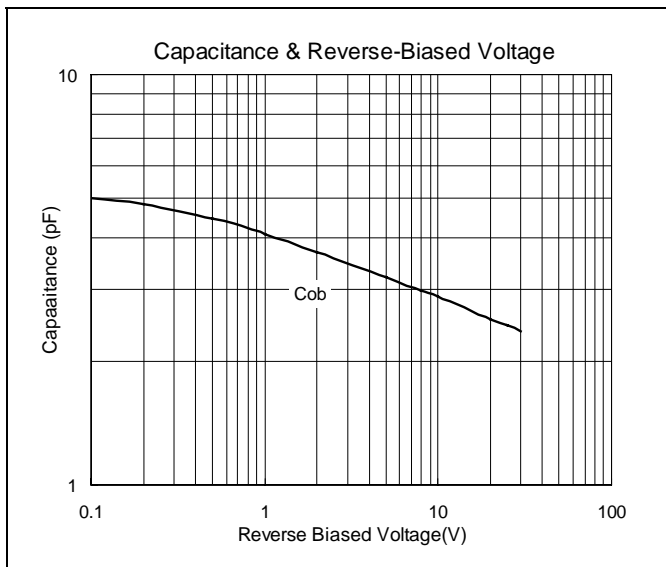
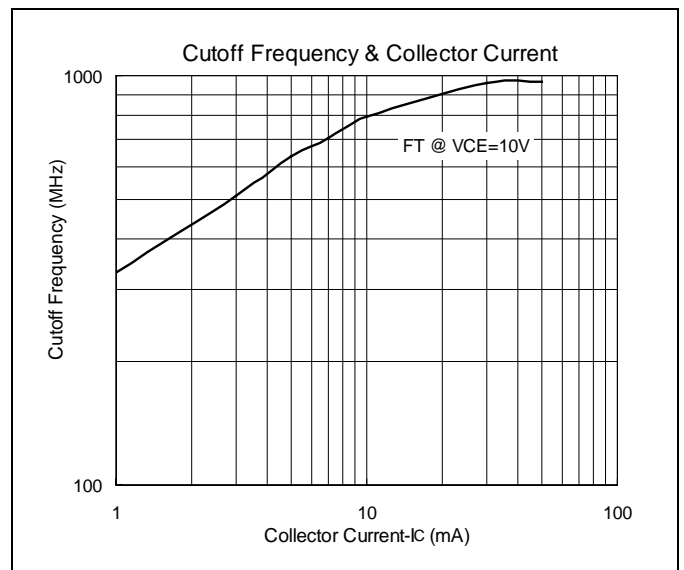
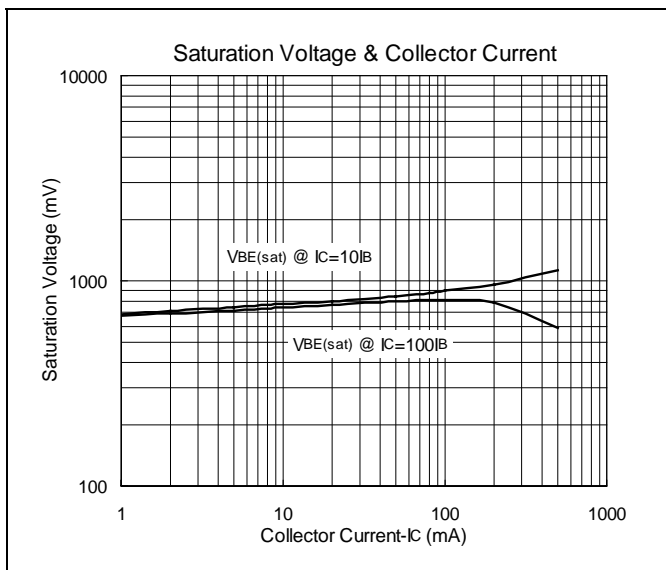
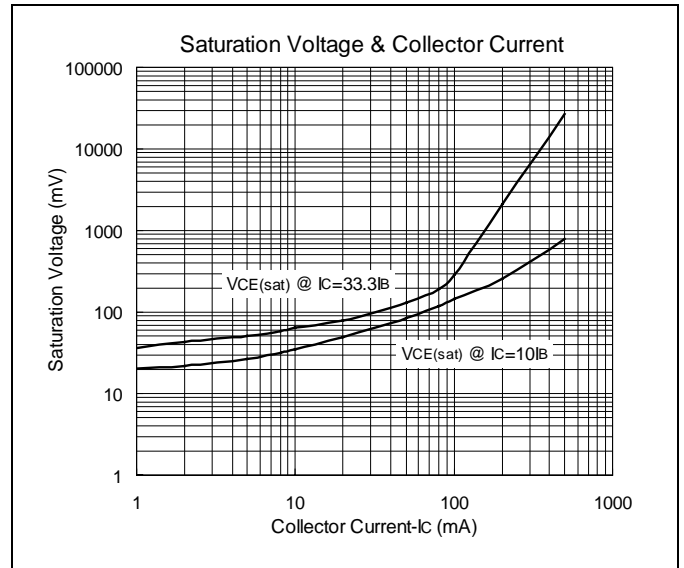
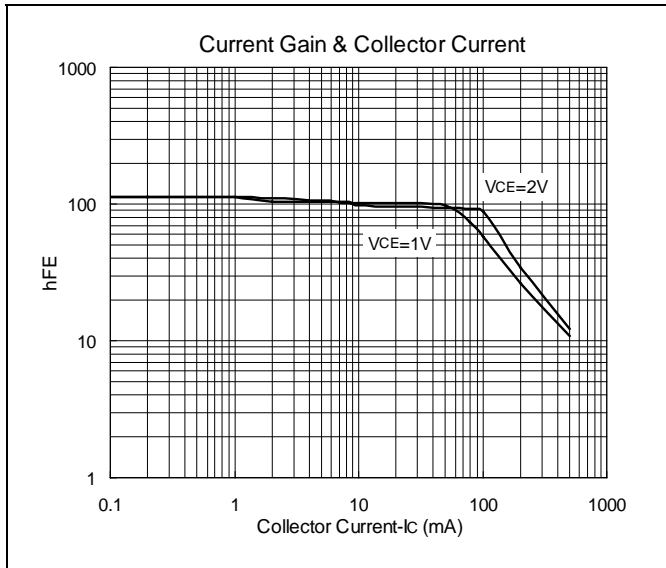
Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BVCBO	40	-	-	V	IC=100uA, IE=0
BVCEO	15	-	-	V	IC=10mA, IB=0
BVEBO	4.5	-	-	V	IE=10uA, IC=0
ICBO	-	-	400	nA	VCB=20V, IE=0
IEBO	-	-	100	nA	VEB=2V, IC=0
*VCE(sat)1	-	-	250	mV	IC=10mA, IB=1mA
*VCE(sat)2	-	-	300	mV	IC=10mA, IB=0.3mA
*VCE(sat)3	-	-	600	mV	IC=100mA, IB=10mA
*VBE(sat)1	700	-	850	mV	IC=10mA, IB=1mA
*VBE(sat)2	-	-	1.5	V	IC=100mA, IB=1mA
*hFE1	40	-	120		IC=10mA, VCE=1V
*hFE2	20	-	-		IC=100mA, VCE=2V
fT	500	900	-	MHz	IC=10mA, VCE=10V, f=100MHz
Cob	-	-	4	pF	VCB=5V, f=1MHz, IE=0

*Pulse Test: Pulse Width ≤380us, Duty Cycles≤2%



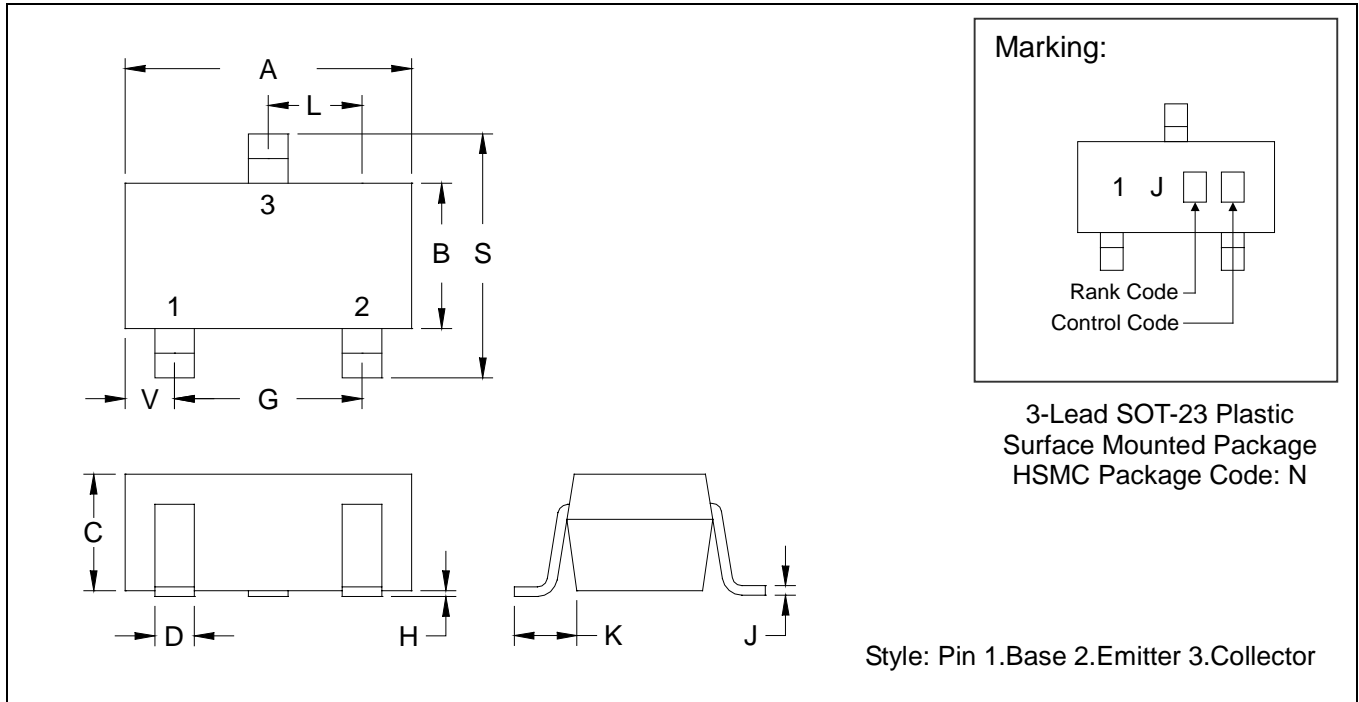


Characteristics Curve





SOT-23 Dimension



*: Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.1102	0.1204	2.80	3.04	J	0.0034	0.0070	0.085	0.177
B	0.0472	0.0630	1.20	1.60	K	0.0128	0.0266	0.32	0.67
C	0.0335	0.0512	0.89	1.30	L	0.0335	0.0453	0.85	1.15
D	0.0118	0.0197	0.30	0.50	S	0.0830	0.1083	2.10	2.75
G	0.0669	0.0910	1.70	2.30	V	0.0098	0.0256	0.25	0.65
H	0.0005	0.0040	0.013	0.10					

- Notes:**
- 1.Dimension and tolerance based on our Spec. dated Sep. 07,1997.
 - 2.Controlling dimension: millimeters.
 - 3.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
 - 4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

Material:

- Lead: 42 Alloy; solder plating
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0

Important Notice:

- All rights are reserved. Reproduction in whole or in part is prohibited without the prior written approval of HSMC.
- HSMC reserves the right to make changes to its products without notice.
- **HSMC semiconductor products are not warranted to be suitable for use in Life-Support Applications, or systems.**
- HSMC assumes no liability for any consequence of customer product design, infringement of patents, or application assistance.

Head Office And Factory:

- **Head Office** (Hi-Sincerity Microelectronics Corp.): 10F.,No. 61, Sec. 2, Chung-Shan N. Rd. Taipei Taiwan R.O.C.
 Tel: 886-2-25212056 Fax: 886-2-25632712, 25368454
- **Factory 1:** No. 38, Kuang Fu S. Rd., Fu-Kou Hsin-Chu Industrial Park Hsin-Chu Taiwan. R.O.C
 Tel: 886-3-5983621~5 Fax: 886-3-5982931